

---

## Contents

---

<b>Foreword 1</b> . . . . .	xi
<b>Foreword 2</b> . . . . .	xv
<b>Preface</b> . . . . .	xix
<b>Chapter 1. Reliability and Innovation: Issues and Challenges</b> . . . . .	1
Claire LARIVOIRE, Fabien MARTY and David DELAUX	
1.1. Introduction . . . . .	1
1.2. Innovation: spearheading competitiveness . . . . .	2
1.3. Reliability: a major issue . . . . .	4
1.4. Reliability in the innovation process. . . . .	7
1.4.1. The management of innovation, the criterion of success for the innovation-reliability parallelism. . . . .	7
1.4.2. Participatory innovation between creatives and technicians. . . . .	8
1.4.3. Supporting open-innovation through collaborative projects . . . . .	8
1.5. Conclusion . . . . .	9
1.6. Bibliography. . . . .	10
<b>Chapter 2. Reliability in the Automotive World</b> . . . . .	11
David DELAUX	
2.1. Introduction: a history of reliability in the automotive world. . . . .	11
2.2. The challenges of automotive reliability: complexity of systems and organizations . . . . .	15

2.3. The economic stakes in automobile reliability . . . . .	20
2.4. An analysis of reliability through the analysis of warranty . . . . .	23
2.5. Conclusion: the future of reliability in the automotive world . . . . .	23
2.6. Bibliography . . . . .	24
<b>Chapter 3. Reliability in the World of Aeronautics</b> . . . . .	27
Tony LHOMMEAU, Régis MEURET and Agnès MATHEVET	
3.1. Introduction . . . . .	27
3.2. Safety and reliability . . . . .	32
3.3. Maintainability/availability. . . . .	34
3.4. Tomorrow's challenges. . . . .	35
3.5. Conclusion . . . . .	38
3.6. Bibliography . . . . .	38
<b>Chapter 4. Reliability in the World of Defense</b> . . . . .	41
Henri GRZESKOWIAK	
4.1. Introduction . . . . .	41
4.2. Operational dependability in the world of defense . . . . .	42
4.3. History of reliability in the world of defense . . . . .	48
4.3.1. History of reliability in the US world of defense . . . . .	48
4.4. Reliability in the field of defense in the US today . . . . .	54
4.4.1. Some observations . . . . .	54
4.4.2. Recommendations for improving this situation . . . . .	55
4.5. Importance of taking into account influential environments in the product life profile. . . . .	56
4.6. Websites dedicated to the dissemination of good reliability practices in the United States . . . . .	58
4.7. French websites dedicated to the dissemination of good practices in the field of reliability in France today. . . . .	65
4.7.1. France's main actors in the field of reliability in interaction with the world of defense. . . . .	65
4.8. Reminder of a few real-life examples in the world of defense. . . . .	69
4.8.1. Case study 1: the KURKS accident . . . . .	69
4.8.2. Case study 2: missile reliability tests at Point Mugu . . . . .	70
4.8.3. Case study 3: reliability tests at the CEAT (Toulouse, France) . . . . .	71
4.8.4. Case study 4: the Falklands War . . . . .	72
4.8.5. Case study 5: air missile and buffeting on a combat aircraft during captive flight . . . . .	72

4.8.6. Case 6: incorrectly taking into account the inrush current variability of a cold start diode . . . . .	73
4.8.7. Lessons learned from these six case studies . . . . .	73
4.9. Conclusion . . . . .	74
4.10. Bibliography . . . . .	75
<b>Chapter 5. The Objectives of Reliability</b> . . . . .	<b>77</b>
Lambert PIERRAT	
5.1. Introduction and objectives . . . . .	77
5.2. Genesis and problem of reliability . . . . .	78
5.2.1. The genesis of reliability . . . . .	78
5.2.2. Predictive problems . . . . .	79
5.3. Concepts and notions of reliability . . . . .	80
5.3.1. Qualitative approach to the life cycle . . . . .	80
5.3.2. Notions of reliability . . . . .	82
5.4. Components and system . . . . .	85
5.5. Objectives of reliability . . . . .	86
5.5.1. Functional characteristics . . . . .	87
5.5.2. Objectives of guaranteed reliability . . . . .	87
5.6. Adequacy of specifications . . . . .	88
5.6.1. Current limitations . . . . .	88
5.6.2. Relevance of the MTTF . . . . .	89
5.7. Methodological approach . . . . .	91
5.7.1. Formulation of the example problem . . . . .	91
5.7.2. All of the on-board components . . . . .	92
5.7.3. “Critical” component . . . . .	93
5.7.4. Statistical approach . . . . .	94
5.8. Conclusion . . . . .	95
5.9. Bibliography . . . . .	96
<b>Chapter 6. “Critical” Components</b> . . . . .	<b>97</b>
Lambert PIERRAT	
6.1. Introduction and objectives . . . . .	97
6.2. Problem of reliability . . . . .	98
6.2.1. Components and system . . . . .	98
6.2.2. Concept of criticality . . . . .	100
6.2.3. Influence on the system’s reliability . . . . .	101
6.3. Estimate for the lifetime of a capacitor . . . . .	105
6.3.1. The problem . . . . .	105
6.3.2. Available information . . . . .	107

6.3.3. Conditions and test results . . . . .	108
6.3.4. The acceleration factor . . . . .	109
6.3.5. Life expectancy . . . . .	113
6.4. Conclusion . . . . .	115
6.5. Bibliography . . . . .	115
<b>Chapter 7. Estimated Reliability Prediction . . . . .</b>	<b>119</b>
Rémy FOUCHEREAU, David DELAUX, Henri GREZOSKOWIAK and Daniel TRIAS	
7.1. Introduction . . . . .	119
7.1.1. Historical benchmarks for the methods and standards of reliability prediction for electronics . . . . .	120
7.1.2. The MIL-HDBK-217F handbook . . . . .	122
7.1.3. The RIAC-HDBK-217+ handbook . . . . .	123
7.1.4. RDF 2000 (UTE C80-810) Reliability Data Handbook . . . . .	125
7.1.5. FIDES guide . . . . .	125
7.1.6. What are the main differences between the handbooks? . . . . .	127
7.1.7. Conclusion . . . . .	128
7.2. Reliability prediction for four critical components . . . . .	128
7.2.1. General remarks . . . . .	128
7.2.2. Electrolytic capacitor . . . . .	129
7.2.3. Film capacitor . . . . .	133
7.2.4. IGBT . . . . .	133
7.2.5. Power inductance . . . . .	136
7.2.6. Power components, which handbooks? . . . . .	137
7.3. Conclusion . . . . .	139
7.4. Bibliography . . . . .	139
<b>Chapter 8. Simulation of Degradation Phenomena in Semiconductor Components in order to Ensure the Reliability of Integrated Circuits . . . . .</b>	<b>143</b>
Insaf LAHBIB, Aziz DOUKKALI, Patrick MARTIN, Guy IMBERT, Philippe DESCAMPS and Dominique DEFOSSEZ	
8.1. Introduction . . . . .	144
8.1.1. History of reliability . . . . .	146
8.1.2. Designing for reliability . . . . .	147
8.2. Mechanisms of degradation in active semiconductor components . . . . .	149
8.2.1. Degradation in MOS transistors . . . . .	149
8.2.2. Degradation in bipolar transistors . . . . .	165
8.2.3. Conclusion . . . . .	176

8.3. Study on the degradation of a ring oscillator . . . . .	177
8.3.1. Introduction . . . . .	177
8.3.2. Presentation of the oscillator . . . . .	177
8.3.3. Study on the aging of the circuit according to these modes of operation . . . . .	178
8.4. Conclusion . . . . .	183
8.5. Bibliography . . . . .	184

**Chapter 9. Estimation of Fatigue Damage  
of a Control Board Subjected to Random Vibration . . . . . 187**

Mayssam JANNOUN, Younes AOUES, Emmanuel PAGNACCO,  
Abdelkhalak EL HAMI and Philippe POUUNET

9.1. Introduction . . . . .	187
9.2. Description of the methodology . . . . .	187
9.3. Finite element modeling . . . . .	188
9.3.1. Geometry, boundary conditions and mechanical properties of materials . . . . .	189
9.3.2. Modal analysis . . . . .	191
9.4. Spectral analysis of random vibrations . . . . .	196
9.4.1. Highly accelerated life tests (HALT) . . . . .	196
9.4.2. Numerical simulations . . . . .	198
9.5. Application of a stationary Gaussian random load . . . . .	203
9.5.1. FE model and sub-modeling technique . . . . .	205
9.6. Estimated fatigue damage . . . . .	207
9.6.1. Time domain study . . . . .	207
9.6.2. Frequency domain study . . . . .	207
9.6.3. Calculation of fatigue damage and comparison of methods . . . . .	208
9.7. Conclusion . . . . .	209
9.8. Bibliography . . . . .	210

**Chapter 10. Study on the Thermomechanical Fatigue  
of Electronic Power Modules for Traction Applications  
in Electric and Hybrid Vehicles (IGBT) . . . . . 213**

Abderahman MAKHLOUFI, Younes AOUES, Abdelkhalak EL HAMI,  
Bouchaib RADI, Philippe POUUNET and David DELAUX

10.1. Introduction . . . . .	213
10.2. Presentation of the power module (IGBT) . . . . .	214
10.3. Different modes of failure for power modules under the effect of thermal cycling . . . . .	216
10.3.1. Breakdown of ceramic substrates . . . . .	216

10.3.2. Solder fatigue: chip–substrate and substrate–base plate . . . . .	217
10.3.3. Fatigue of the metallization in the aluminum of the component . . . . .	218
10.4. The physical phenomena involved . . . . .	218
10.4.1. Thermal phenomena . . . . .	218
10.4.2. Electrothermal phenomena. . . . .	222
10.4.3. Mechanical phenomena . . . . .	224
10.5. Modeling of physical phenomena (simulation through the finite element method). . . . .	228
10.5.1. Strong coupling of electro-thermomechanical modeling . . . . .	229
10.5.2. The weak coupling of electro-thermomechanical modeling . . . . .	233
10.6. Digital models of IGBT power demonstrator failure . . . . .	235
10.6.1. Failure model of electrical wires by thermal fatigue. . . . .	235
10.6.2. Failure model of solder by thermal fatigue . . . . .	246
10.7. Conclusion. . . . .	249
10.8. Bibliography . . . . .	250
<b>Chapter 11. Exploration of Thermal Simulation Aimed at Consolidating the Reliability Approach of Mechatronic Components</b> . . . . .	253
Sébastien YON and Eric ROULAND	
11.1. Introduction . . . . .	253
11.2. Modeling, input data and boundary conditions . . . . .	254
11.2.1. Inverter converter and heat sink. . . . .	254
11.2.2. Thermal modeling of the component. . . . .	256
11.2.3. Fluid modeling. . . . .	258
11.2.4. Global modeling of the system . . . . .	259
11.2.5. Boundary conditions and input data . . . . .	260
11.3. Operation results of the digital model. . . . .	263
11.3.1. Results of the digital simulations . . . . .	263
11.3.2. Reliability laws . . . . .	270
11.4. Digital tool: EleXTherm . . . . .	273
11.5. Bibliography . . . . .	273
<b>Appendix</b> . . . . .	275
<b>List of Authors</b> . . . . .	279
<b>Index</b> . . . . .	281